



PRESS RELEASE

## SPS introduces Sub-Lam<sup>®</sup> to support large-volume production of payment cards

**Smart Packaging Solutions (SPS) is bringing its contribution to the spread of dual interface payment cards with its newly developed Sub-Lam<sup>®</sup>, dedicated to large volume production.**

**ROUSSET, FRANCE, November 2, 2015** – Smart Packaging Solutions, a world leader in dual interface banking and eID documents, is expanding its offer with “Sub-Lam<sup>®</sup>,” a laminate built with an inlay and two PVC sheets dedicated to large volumes of dual interface payment cards.

Sub-Lam<sup>®</sup> consists in an inlay, with an etched antenna, laminated between two PVC sheets. This combination brings rigidity and stability guaranteeing an easy integration process for card manufacturers. Sub-Lam<sup>®</sup> has been developed by SPS as an evolution of the company’s S-Lam, already adopted by numerous card manufacturers worldwide. Thanks to its new manufacturing process, Sub-Lam<sup>®</sup> is ideally adapted to large production volumes.

As Sub-Lam<sup>®</sup> is manufactured in roll, it is compatible with very large-volume manufacturing. Sub-Lam<sup>®</sup> facilitates the handling with a full compliancy with automatic collating process, assuring all card manufacturers confronted to a fast ramp-up of their contactless or dual interface card production that they will easily adapt to new demands from card issuers.

Olivier Brunet, Product & Marketing director, SPS, declares “With the addition of Sub-Lam<sup>®</sup> to our range of products, we are bringing our support to large volume manufacturers involved in the major ongoing EMV migrations.”

Sub-Lam<sup>®</sup> is readily available from SPS. Sub-Lam<sup>®</sup> is part of the eBoost PAY<sup>®</sup> product line, which offers a unique and patented technology for secure and reliable payment and transport cards enabling a contact & contactless interface. The eBoost PAY<sup>®</sup> product line builds upon SPS numerous references for payment and transport applications and includes dual interface modules (Dual 6 and Dual 8) and inlays, S-Lam<sup>®</sup> and Sub-Lam<sup>®</sup>. Already, SPS customers have received more than 45 currently active certifications or type approvals from payment networks for their products associating various chips from all semiconductor vendors, with different operating systems.



SPS will be exhibiting on booth 4L061, at Cartes Secure Connexions on November 17-19, in Paris Nord Villepinte, France.

**About SPS**

Smart Packaging Solutions is specialized in the design, manufacturing and sale of contactless solutions dedicated to ID cards, e-passport and dual interface banking cards. Headquartered in Rousset, France, with a subsidiary in Singapore, SPS employs 120 people. Part of the French group 'Imprimerie Nationale', the company specializes in contactless and dual-interface products, with a recognized micro packaging expertise. SPS has filed over 120 patents supporting its exclusive technologies. More information at [www.s-p-s.com](http://www.s-p-s.com)

**Contact**

Olivier BRUNET, Product & Marketing director, SPS, [contact@s-p-s.com](mailto:contact@s-p-s.com),  
tel: +33 4 42 53 84 44

SPS is part of the Imprimerie Nationale Group

**About the Imprimerie Nationale Group**

The Imprimerie Nationale Group is a high tech company, expert in engineering solutions for official credentials, the global management of identities and rights, the protection of sensitive data and controlling flows and complex printing processes.

The Imprimerie Nationale Group supports organisations in the public and private sectors in the production of credentials, the securing of documents and in the integration of trust services technological solutions. The Imprimerie Nationale produces more than 25 million secure credentials each year, including the French biometric passport.